



## Material Content Data Sheet



<b>Sales Product Name</b>		IPD50N03S4L-06		<b>Issued</b>		29. August 2013			
<b>MA#</b>		MA000940338							
<b>Package</b>		PG-TO252-3-11		<b>Weight*</b>		369.52 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	1.143	0.31	0.31	3092	3092	
leadframe	non noble metal	iron	7439-89-6	0.234	0.06		635		
	inorganic material	phosphorus	7723-14-0	0.070	0.02		190		
	non noble metal	copper	7440-50-8	234.187	63.37	63.45	633766	634591	
wire	non noble metal	aluminium	7429-90-5	1.907	0.52	0.52	5160	5160	
encapsulation	organic material	carbon black	1333-86-4	1.268	0.34		3432		
	plastics	epoxy resin	-	22.191	6.01		60054		
	inorganic material	silicondioxide	60676-86-0	103.346	27.97	34.32	279679	343165	
leadfinish	non noble metal	tin	7440-31-5	3.740	1.01	1.01	10121	10121	
plating	non noble metal	nickel	7440-02-0	0.091	0.02		246		
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.02	1	247	
solder	noble metal	silver	7440-22-4	0.033	0.01		91		
	non noble metal	tin	7440-31-5	0.027	0.01		72		
	non noble metal	lead	7439-92-1	1.279	0.35	0.37	3461	3624	
*deviation	< 10%					Sum in total:	100.00		1000000

### Important Remarks:

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